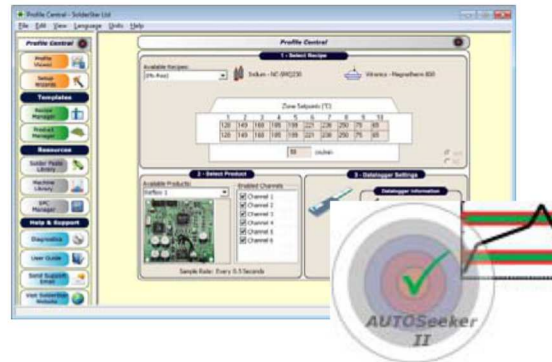


solderstar[®]

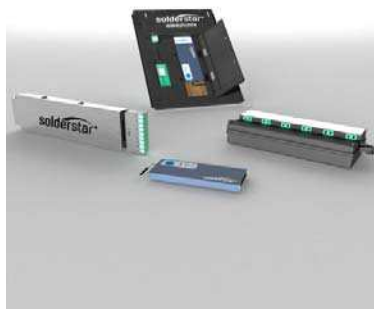
Temperature Profiling Systems

Documentation 2012

solderstar[®]
Lite



3ⁱⁿ ONE
REFLOW - WAVE - VAPOUR



DISTRIBUTEUR FRANCE
J2C COMPOSANT
4 Avenue du grand chêne - 34270 Saint Mathieu de Treviers
Tél. : 04.67.59.90.39 - Mail : j2c@j2c.fr



SolderStar LITE - 4 Channel Reflow Profiling System

System Part Number: R-0425



System Equipment Included

Part No.

Description

DL-NEP4

SolderStar Neptune 4 channel USB datalogger

Sensor Type	4 x Type K
Measurement Accuracy	±1 C
Measurement Resolution	0.02°C
Measurement Range	-150 - 500 C
Fastest Sample Period	0.1 Sec
Slowest Sample Period	1 Hour
Rechargeable Battery Power	NiMH
Maximum Operating Temperature	85°C
Datalogger Memory Size	65000 Points
Communication Method	USB

Supplied with calibration certificate

TP-GF100-4

Thermocouple Pack

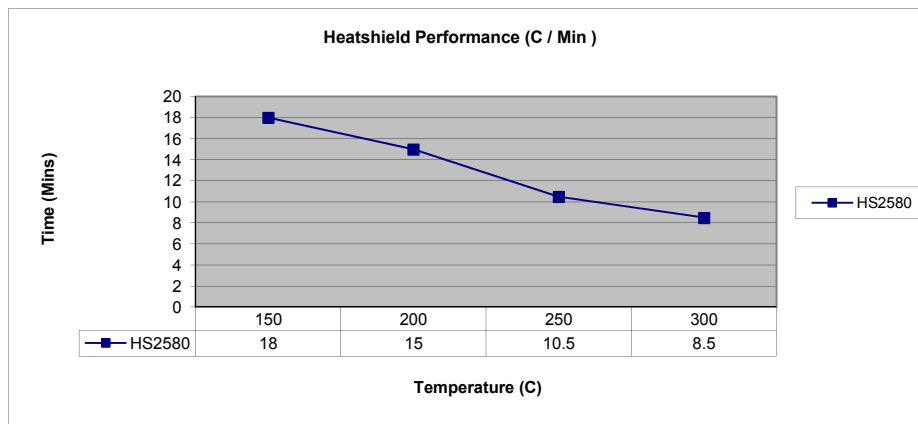
Includes 4 x 100cm Glass Fibre type K thermocouples

Solderstar thermocouples are manufactured from special limits of error wire to EN60584-2 Class 1

HS2080

25mm Thermal Heatshield

Construction	Stainless Steel
Dimensions	25mm x 80mm x 280mm



DC001

USB Communication/Recharge cable

Standard USB A to Mini B

SW-R-STD

Profile Central PC Analysis Software

Includes PC software on CDROM

Profile Prediction Software Module (Manual)

Wave Solder Support Module

SPC Manager Software

EC001

SolderStar Equipment Case

Hinged hard plastic equipment case, full custom foam protection insert

SolderStar LITE - Accessories

Part No.

Description

AC-SWAUTO

AUTOSeeker Profile Optimisation Software

AC-RC-001

Adjustable Reflow Carrier

J2C COMPOSANT

4 Avenue du grand Chêne - 34270 St Mathieu de Treviers

Tél. : 04.67.59.90.39 Mail : j2c@j2c.fr

System Part Number: R-0625P

System Equipment Included

Part No.

Description

DL-NEPSLU

SolderStar Neptune 6 channel USB datalogger



Sensor Type	6 x Type K
Measurement Accuracy	±1 C
Measurement Resolution	0.02°C
Measurement Range	-150 - 500 C
Fastest Sample Period	0.1 Sec
Slowest Sample Period	1 Hour
Rechargeable Battery Power	NiMH
Maximum Operating Temperature	85°C
Datalogger Memory Size	65000 Points
Communication Method	USB or 2.4Ghz Wireless (Optional)

Supplied with calibration certificate

SL-HS-6

6 Channel Smartlink Adapter

6 Channel Type K Smartlink adapter



TP-GF100-6

Thermocouple Pack

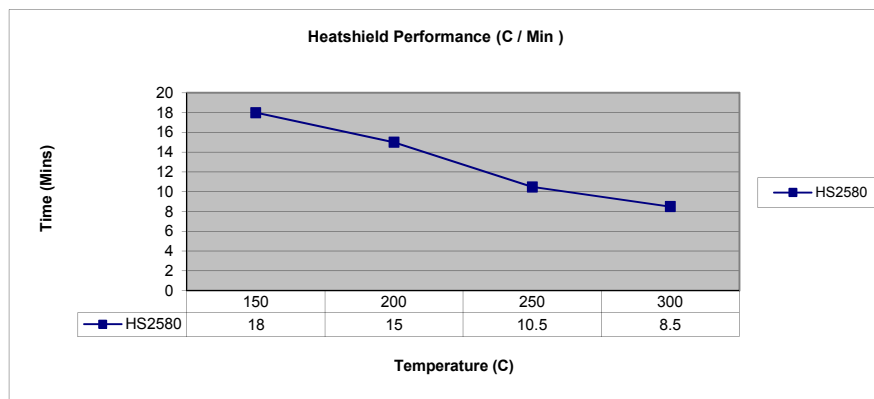
Includes 6 x 100cm Glass Fibre type K thermocouples

Solderstar thermocouples are manufactured from special limits of error wire to EN60584-2 Class 1

HS2580-SL

25mm Thermal Heatshield

Construction	Stainless Steel
Dimensions	25mm x 80mm x 280mm



DC001

USB Communication/Recharge cable

Standard USB A to Mini B

SW-R-STD

Profile Central PC Analysis Software

Includes PC software on CDROM
Profile Prediction Software Module (Manual)
Wave Solder Support Module
SPC Manager Software

EC001

SolderStar Equipment Case

Hinged hard plastic equipment case, full custom foam protection insert

SolderStar PRO - Accessories (see Page 9 for more details)

Part No.

Description

AC-SWAUTO

AUTOSeeker Profile Optimisation Software

AC-RFMOD

2.4Ghz Wireless Telemetry Kit

AC-WSPRO

WaveShuttle PRO High Performance Wave Solder Analyser

AC-DP-001

DeltaPRObe Reflow Oven Performance Fixture

AC-RC-001

Adjustable Reflow Carrier

AC-VPPACK

Vapour Phase Pack (Thermal Barrier + Software)

SolderStar PRO - 9 Channel Reflow Profiling System

System Part Number: R-0925P



System Equipment Included

Part No.

Description



DL-NEPSLU

SolderStar Neptune SL USB Rechargeable datalogger

Sensor Type	Type K
Measurement Accuracy	±1 C
Measurement Resolution	0.02°C
Measurement Range	-150 - 500 C
Fastest Sample Period	0.1 Sec
Slowest Sample Period	1 Hour
Battery Power	NIMH
Maximum Operating Temperature	85°C
Datalogger Memory Size	120000 Points
Communication Method	USB or 2.4Ghz Wireless (Optional)

Supplied with calibration certificate

SL-HS-9

9 Channel Smartlink Adapter

9 Channel Type K Smartlink adapter



TP-GF100-9

Thermocouple Pack

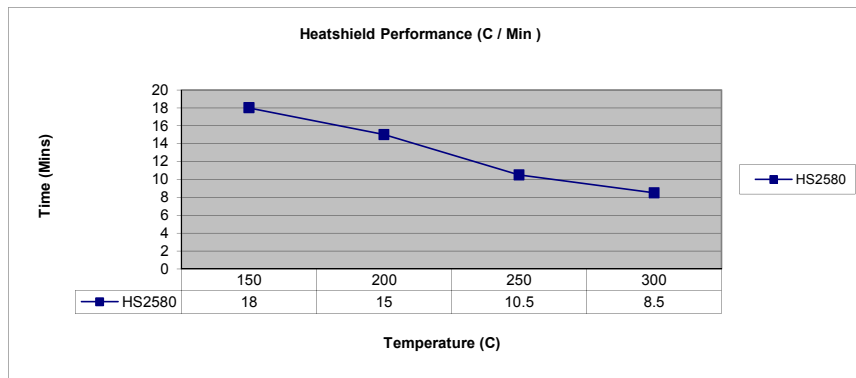
Includes 9 x 100cm Glass Fibre type K thermocouples (480C Rated)

Solderstar thermocouples are manufactured from special limits of error wire to EN60584-2 Class 1

HS2580-SL

25mm Thermal Heatshield - Smartlink Ready

Construction	Stainless Steel
Dimensions	25mm x 80mm x 280mm



DC001

USB Communication/Recharge cable

Standard USB A to Mini B

SW-R-STD

Profile Central PC Analysis Software

Includes PC software on CDROM
Profile Prediction Software Module (Manual)
Wave Solder Support Module
SPC Manager Software

EC001

SolderStar Equipment Case

Hinged hard plastic equipment case, full custom foam protection insert

SolderStar PRO - Accessories (see Page 9 for more details)

Part No.

Description

AC-SWAUTO

AUTOSeeker Profile Optimisation Software

AC-RFMOD

2.4Ghz Wireless Telemetry Kit

AC-WSPRO

WaveShuttle PRO High Performance Wave Solder Analyser

AC-DP-001

DeltaPRObe Reflow Oven Performance Fixture

AC-RC-001

Adjustable Reflow Carrier

AC-VPPACK

Vapour Phase Pack (Thermal Barrier + Software)

J2C COMPOSANT

**4 Avenue du grand Chêne - 34270 St Mathieu de Treviers
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SolderStar PRO - 12 Channel Reflow Profiling System

System Part Number: R-1225P



System Equipment Included

Part No.

Description



DL-NEPSLU

SolderStar Neptune SL USB Rechargeable datalogger

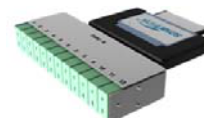
Sensor Type	Type K
Measurement Accuracy	±1 C
Measurement Resolution	0.02°C
Measurement Range	-150 - 500 C
Fastest Sample Period	0.1 Sec
Slowest Sample Period	1 Hour
Battery Power	NiMH
Maximum Operating Temperature	85°C
Datalogger Memory Size	120000 Points
Communication Method	USB or 2.4Ghz Wireless (Optional)

Supplied with calibration certificate

SL-HS-12

12 Channel Smartlink Adapter

12 Channel Type K Smartlink adapter



TP-GF100-12

Thermocouple Pack

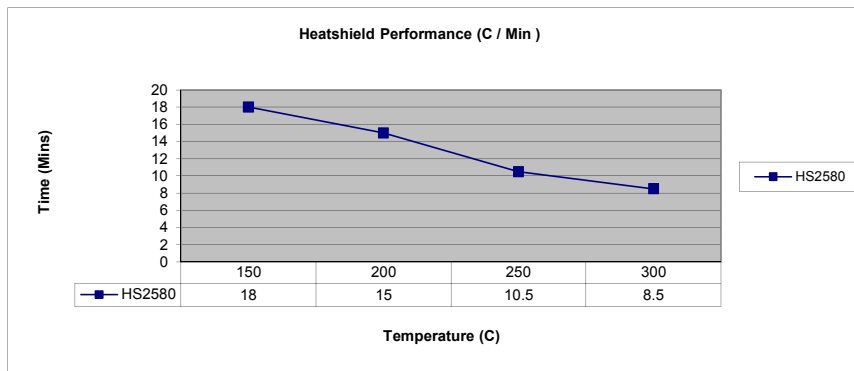
Includes 12 x 100cm Glass Fibre type K thermocouples (480C Rated)

Solderstar thermocouples are manufactured from special limits of error wire to EN60584-2 Class 1

HS2580-SL

25mm Thermal Heatshield - Smartlink Ready

Construction	Stainless Steel
Dimensions	25mm x 80mm x 280mm



DC001

USB Communication/Recharge cable

Standard USB A to Mini B

SW-R-STD

Profile Central PC Analysis Software

Includes PC software on CDROM
Profile Prediction Software Module (Manual)
Wave Solder Support Module
SPC Manager Software

EC001

SolderStar Equipment Case

Hinged hard plastic equipment case, full custom foam protection insert

SolderStar PRO - Accessories (see Page 9 for more details)

Part No.

Description

AC-SWAUTO

AUTOSeeker Profile Optimisation Software

AC-RFMOD

2.4Ghz Wireless Telemetry Kit

AC-WSPRO

WaveShuttle PRO High Performance Wave Solder Analyser

AC-DP-001

DeltaPRObe Reflow Oven Performance Fixture

AC-RC-001

Adjustable Reflow Carrier

AC-VPPACK

Vapour Phase Pack (Thermal Barrier + Software)

J2C COMPOSANT

4 Avenue du grand Chêne - 34270 St Mathieu de Treviers
Tél. : 04.67.59.90.39 Mail : j2c@j2c.fr

SolderStar PRO - 16 Channel Reflow Profiling System

System Part Number: R-1625P



System Equipment Included

Part No.

Description

DL-NEPSLU

SolderStar Neptune SL USB Rechargeable datalogger



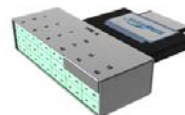
Sensor Type	Type K
Measurement Accuracy	±1 C
Measurement Resolution	0.02°C
Measurement Range	-150 - 500 C
Fastest Sample Period	0.1 Sec
Slowest Sample Period	1 Hour
Battery Power	NiMh
Maximum Operating Temperature	85°C
Datalogger Memory Size	120000 Points
Communication Method	USB or 2.4Ghz Wireless (Optional)

Supplied with calibration certificate

SL-HS-16

16 Channel Smartlink Adapter

16 Channel Type K Smartlink adapter



TP-GF100-16

Thermocouple Pack

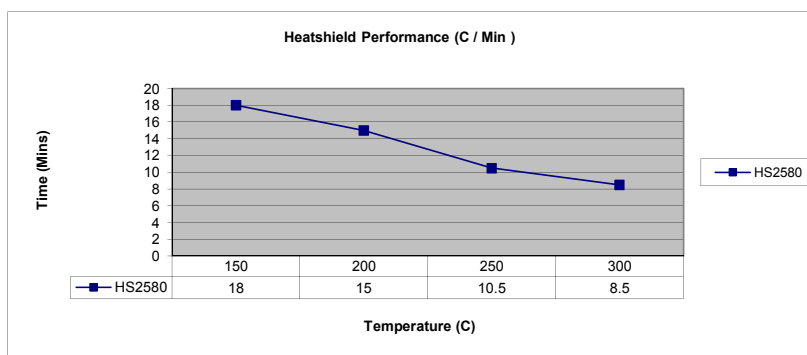
Includes 16 x 100cm Glass Fibre type K thermocouples (480C Rated)

Solderstar thermocouples are manufactured from special limits of error wire to EN60584-2 Class 1

HS2580-SL

25mm Thermal Heatshield - Smartlink Ready

Construction	Stainless Steel
Dimensions	25mm x 80mm x 280mm



DC001

USB Communication/Recharge cable

Standard USB A to Mini B

SW-R-STD

Profile Central PC Analysis Software

Includes PC software on CDROM

Profile Prediction Software Module (Manual)

Wave Solder Support Module

SPC Manager Software

EC001

SolderStar Equipment Case

Hinged hard plastic equipment case, full custom foam protection insert

SolderStar PRO - Accessories (see Page 9 for more details)

Part No.

Description

AC-SW AUTO

AUTOSeeker Profile Optimisation Software

AC-RF MOD

2.4Ghz Wireless Telemetry Kit

AC-WSPRO

WaveShuttle PRO High Performance Wave Solder Analyser

AC-DP-001

DeltaPRObe Reflow Oven Performance Fixture

AC-RC-001

Adjustable Reflow Carrier

AC-VPPACK

Vapour Phase Pack (Thermal Barrier + Software)

J2C COMPOSANT

4 Avenue du grand Chêne - 34270 St Mathieu de Treviers
Tél. : 04.67.59.90.39 Mail : j2c@j2c.fr



Wave Shuttle PRO - Wave Solder Analyser (Wave Only - Solution)
System Includes Pallet + Datalogger for standalone Wave Solder solution
For combined system for reflow/wave : Select PRO Reflow system + P/N AC-WSPRO
E.g: R-0625P + AC-WSPRO

System Part Number: W-1004



System Equipment Included

Part No.

Description



DL-NEPSLU

SolderStar Neptune SL USB Rechargeable datalogger

Sensor Type	Type K
Measurement Accuracy	±1 C
Measurement Resolution	0.02°C
Measurement Range	-150 - 500 C
Fastest Sample Period	0.1 Sec
Slowest Sample Period	1 Hour
Battery Power	NiMH
Maximum Operating Temperature	85°C
Datalogger Memory Size	120000 Points
Communication Method	USB

Supplied with calibration certificate

AC-WSPRO

WaveShuttle PRO High Performance Wave Solder Analyser

High performance analyser for use on medium/large machines. High reliability Wave Solder Analyser with additional bottom side sensors for detailed solder wave calibration and process control.

Temperature Measurement Sensor	Type K
Wave Measurement Sensor	Titanium
Pallet Side Rails	Titanium
Temperature Measurement Points	5 (See Figure 1)
Wave Measurement Points	22 (See Figure 2)
Wave Measurement Rate	0.01 Seconds

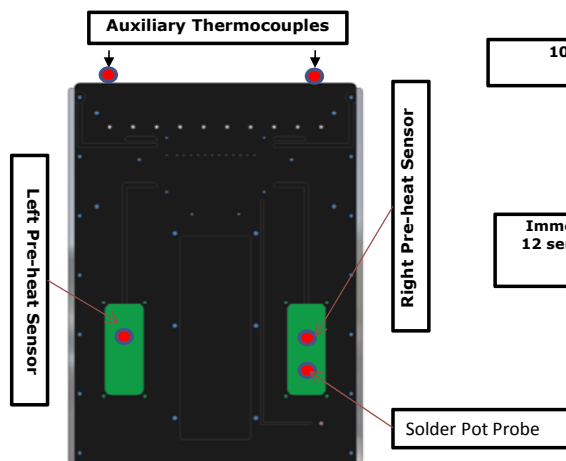


Figure 1
WaveShuttle - PRO Top Side
Temperature Positions

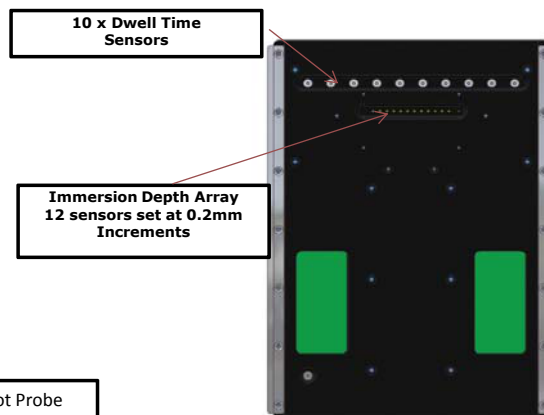


Figure 2
WaveShuttle PRO Bottom Side
Contact Positions

DC001

USB Communication/Recharge cable

Standard USB A to Mini B

SW-W-STD

Wave Central PC Analysis Software

Includes PC software on CDROM
 SPC Manager Software
 Hardcopy User Guide

EC002

SolderStar Equipment Case

Equipment Bag



SolderStar PRO - 6 Vapour Phase Profiling System

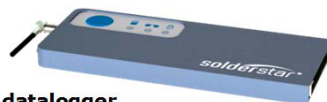
System Part Number: VP-0640P



System Equipment Included

Part No.

Description



DL-NEPSLU

SolderStar Neptune SL USB Rechargeable datalogger

Sensor Type	Type K
Measurement Accuracy	±1 C
Measurement Resolution	0.02°C
Measurement Range	-150 - 500 C
Fastest Sample Period	0.1 Sec
Slowest Sample Period	1 Hour
Rechargeable Battery Power	NiMH
Maximum Operating Temperature	85°C
Datalogger Memory Size	65000 Points
Communication Method	USB or 2.4Ghz Wireless (Optional)

Supplied with calibration certificate

TP-GF100-6

Thermocouple Pack

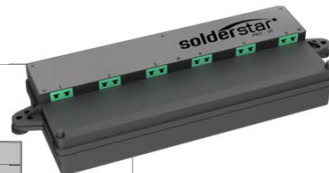
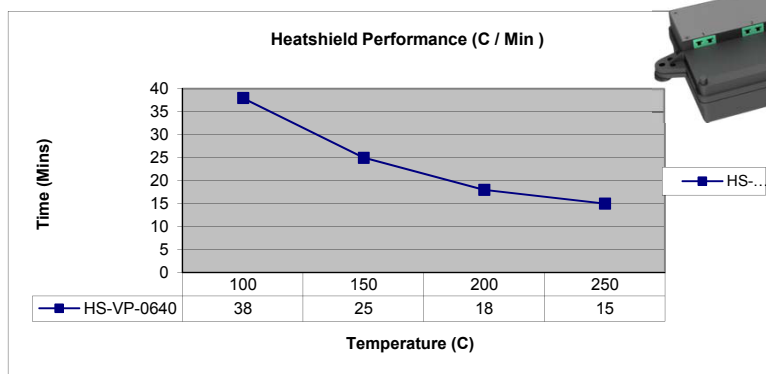
Includes 6 x 100cm Glass Fibre type K thermocouples

Solderstar thermocouples are manufactured from special limits of error wire to EN60584-2 Class 1

HS-VP-0640

6 Channel Vapour Phase Barrier (for SolderStar PRO USB)

Construction	Aluminium
Weight	525g



DC001

USB Communication/Recharge cable

Standard USB A to Mini B

SW-VR-STD

Profile Central PC Analysis Software

Includes PC software on CDROM

Profile Prediction Software Module (Manual)

Vapour Phase Solder Support Module

SPC Manager Software

EC001

SolderStar Equipment Case

Hinged hard plastic equipment case, full custom foam protection insert

Part No.







AC-RFMOD

SolderStar PRO - Accessories

Description

2.4Ghz Wireless Telemetry Kit

SolderStar PRO - Accessories (Detailed)

Part No.	Description	
AC-SWAUTO 	AUTOSeeker Profile Optimisation Software <p>The AUTOSeeker is an optional software module which allows profiles to be optimised automatically. A profile is first captured from a test PCB, the Autoseeker can searches for the optimal set points for the oven. Profiles can be solved to give the absolute optimum, faster throughput or use less energy.</p>	
AC-RFMOD 	2.4Ghz Wireless Telemetry Kit <p>The Wireless Telemetry option all connectionless datalogger setup and viewing of profiles live to the computer as they happen. Downloading of data stored in memory is also possible. Live battery status and internal datalogger temperatures are fed to the computer while the datalogger passes through the machine allowing costly machine jams to be quickly detected. The system uses an innovative self-healing Zigbee network, with this approach transmitted data is never lost and long transmission ranges can be achieved with additional repeaters.</p>	
AC-WSPRO 	WaveShuttle PRO High Performance Wave Solder Analyser <p>The AC-WPRO extends the use of a SolderStar PRO Reflow system for use on the wave solder machine. It is compatible with R-0625P, R-0925P, R-1225P and R-1625P. <u>The datalogger from the reflow system</u> is connected to the pallet to measure all key parameters including wave height in a single pass.</p>	
AC-DP-001 	DeltaPRObe Reflow Oven Performance Fixture <p>The AC-DP-001 is compatible with R-0625P, R-0925P, R-1225P and R-1625P. The datalogger from the reflow system is connected to the DeltaPRObe to provide a convenient fixture to test the repeatability of the reflow oven. A 'golden' process profile is captured by the sensors, this can then be used to perform 'capture and compare' measurement periodically without the need for fragile test boards.</p>	
AC-RC-001 	Adjustable Reflow Carrier <p>The AC-RC-001 is an adjustable carrier that is used to safely transport your profiling system through the reflow process on the conveyor. Adjustment from 120mm - 450mm is possible, the system is manufactured from stainless steel and compatible with all Solderstar Heatshield types. Height adjustment on the side rails is also possible allowing use of the system on very low height tunnels</p>	
AC-VPPACK 	Vapour Phase Pack (Thermal Barrier + Software) <p>The AC-VPPACK is compatible with R-0625P, R-0925P, R-1225P and R-1625P. The datalogger from the reflow system is connected to the Vapour Phase barrier to provide sealed and high thermal performance barrier. This can be passed into the process along with the PCB to capture thermal profiles at component level.</p>	